

## Ameba-Z

# SINGLE-CHIP 802.11b/g/n 1T1R WLAN SoC

# DATASHEET

(CONFIDENTIAL: Development Partners Only)

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This document is intended for the software engineer's reference and provides detailed programming information.

Though every effort has been made to ensure that this document is current and accurate, more information may have become available subsequent to the production of this guide.

#### **REVISION HISTORY**

Revision	Release Date	Summary
1.0	2016/09/01	Change chapter organization
		Change features
~ (		Add timer & RTC datasheet
		Add all peripherals features
		Update table list
0		Update package and pin description
1.1	2016/09/01	Add exception table
1.2	2016/09/02	Add package, pin number and dimension information
1.3	2016/10/21	Fix some errors
1.4	2016/11/03	Advanced time just have 2 groups
1.5	2016/11/29	Fix some errors
1.6	2016/12/09	Add ADC pin definitions
1.7	2016/12/15	Add RTL8710BN-L0 Specification
1.8	2016/12/22	Add 3.3V ADC channel for 8710BN(QFN32)
1.9	2016/12/28	Change SPS_LDO_SEL description

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Revision	Release Date	Summary
2.0	2017/02/13	Change 8711BG to 8711BU (QFN68 with USB)
		Add backup register spec.
2.1	2017/02/27	Add ordering information
2.2	2017/03/27	Remove 8711BN
2.3	2017/04/10	Change ADC Features in chapter 18.
3.0	2017/09/29	Add 8710BX & 8710BL.

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### 1. Product Overview

### 1.1. General Description

Ameba-Z is a highly integrated single-chip low power 802.11n Wireless LAN (WLAN) network controller. It combines an ARM-CM4 MCU, WLAN MAC, a 1T1R capable WLAN baseband, and RF in a single chip. It also provides a bunch of configurable GPIOs which are configured as digital peripherals for different applications and control usage.

Ameba-Z integrates internal memories for complete WIFI protocol functions. The embedded memory configuration also provides simple application developments.

### 1.2. Ordering Information

Part Number	Package	Status
RTL8710BN-A0-CG	QFN32	MP
RTL8711BU-A0-CG	QFN68	MP
RTL8710BL-A0-CG	QFN32	MP@Q4
RTL8710BX-A0-CG	QFN32	MP@Q4



### 1.3. Features

Table 1-1 Ameba-Z Features

Feature list		RTL8711BU-A0	RTL8710BN-A0	RTL8710BL-A0	RTL8710BX-A0
Package	trays and tape-in-reel	(8x8mm^2)	(5x5mm^2)	(5x5mm^2)	(5x5mm^2)
		QFN68	QFN32	QFN32	QFN32
Integrated	Core type	ARM CM4F	ARM CM4F	ARM CM4F	ARM CM4F
core	Core clock maximum	125MHz	125MHz	125MHz	62.5MHz
	freq.			<b>\</b>	
	Internal SRAM	256KB	256KB	256KB	256KB
	External FLASH	128M Bytes	128M Bytes	128M Bytes	128M Bytes
		410	410	210	210
FPU	Float process unit	Yes	Yes	Yes	Yes
SWD/JTAG	. 0	SWD	SWD	SWD	SWD
Backup	Backup register for	16B	16B	16B	16B
register	power save				
Boot Reason	SystemReset/WDG/BOR	Yes	Yes	Yes	Yes
Security	Security Boot	6	0	1	0
	2 flash Encryption	8	2	8	4
	3 Trust-Zone Lite (4KB)	3	3	4	4 .
	4 SSL/TLS	4	4	^	
WIFI	802.11 B/G/N	Yes	Yes	Yes	Yes
HT40	70	Yes	Yes	Yes	NO
BOR	BOR Detection	Yes	Yes	Yes	Yes
GPIO	IN/OUT/INT	39	17	10	17
Ext. 32K	External 32K	1	1	0	0
Dsleep	Deep sleep wake pin	4	4	2	4
Wakepin					



### 1.4. Peripherals

Table 1-2 Ameba-Z Peripherals

Feature list			RTL8711BU-A0	RTL8710BN-A0	RTL8710BL-A0	RTL8710BX-A0
peripherals	UART	Normal-UART	2	1	1	1
		Log-UART	1	1	1	1
	SPI Master	Max. 31.25Mbps	1	1	0	1 \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
	SPI Slave	Max. 31.25Mbps	1	1	0	1
	I2C	Max. 400Kbps	2	2	2	2
	ADC	VBAT	0~5V	0~5V	NA	NA
		Normal	0~3.3V (X2)	NA	NA	NA
	GDMA	2*6 channels	2	2	2	2
	I2S	6	1	0	0	0
	RTC	D/H/M/S	1	1	1	1
		OUTPUT	1	1	1	1
	Timer	Basic	4	4	4	4
		(32K)				
0		Advanced (XTAL)	2	2	2	2
	PWM	OUTPUT	6	6	4	6
		INPUT Capture	2	2	1	2
	WDG	Watch Dog	1	1	1	1
	USB device		1	0	0	0
	SDIO 2.0		1	1	0	1
	Device					



### 1.5. Package Types and Pin Descriptions

#### 1.5.1. RTL8710BN-A0 (QFN32)

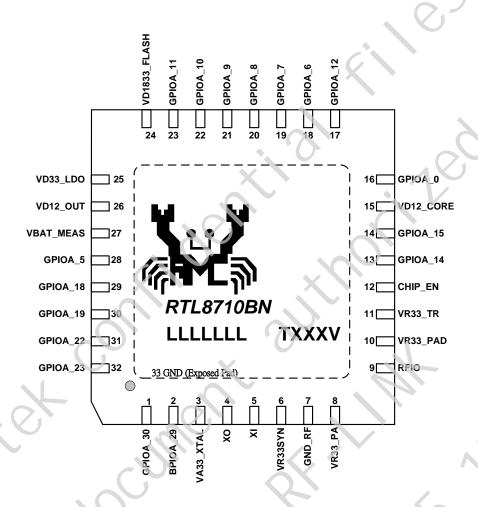


Figure 1 RTL8710BN-A0 QFN32 Pin Assignments



### 1.5.2. RTL8710BX-A0 (QFN32)

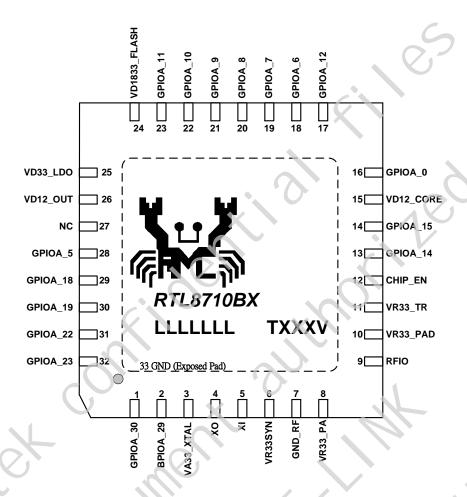


Figure 2 RTL8710BX-A0 QFN32 Pin Assignments



### 1.5.3. RTL8710BL-A0 (QFN32)

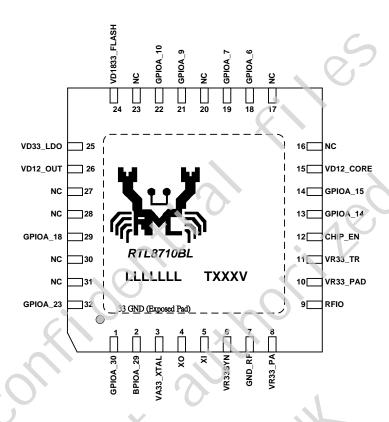


Figure 3 RTL8710BL-A0 QFN32 Pin Assignments



### 1.5.4. RTL8711BU-A0 (QFN68)

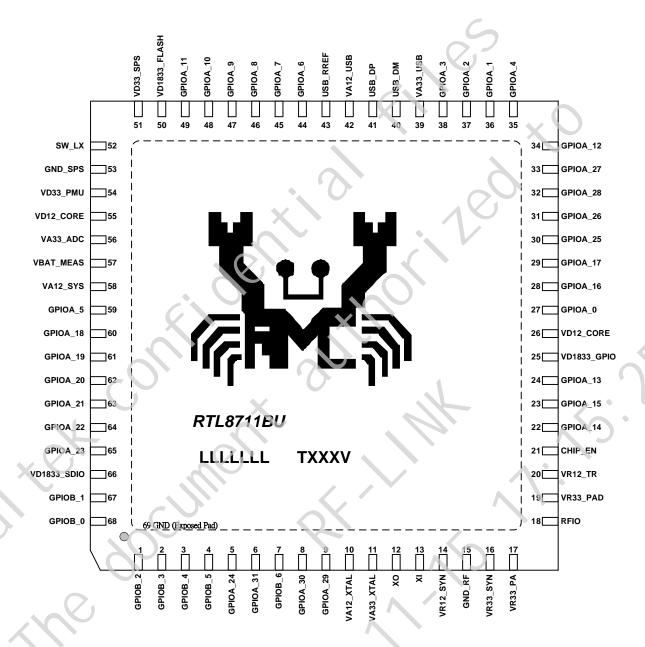


Figure 4 RTL8711BU-A0 QFN68 Pin Assignments

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### 1.6. Pin Descriptions

The following signal type codes are used in the tables:

Table 1-3 Pin Description

I:	Input	<i>O</i> :	Output
T/S:	Tri-State bi-directional input/output pin	S/T/S:	Sustained Tri-State
O/D:	Open Drain	P:	Power pin

### 1.6.1. Power On Trap Pin

Table 1-4 Power On Trap Pins

Symbol	Туре	QFN68	QFN32	Description
TEST_MODE_SEL	I	27	16	Shared with GP OA_0  1: Enter into test/debug mode  0: Normal operation mode
UART_DOWNLOAD	1_	8	1	Shared with GPIOA_30
¥			X	1: Boot from flash 0: Download image from UART
SPS_LDO_SEL	I	38	NA	Shared with GPIOA_3  1: LDO  0: SWR



### 1.6.2. RF pin

Table 1-5 RF pin

Symbol	Туре	QFN68	QFN32	Description	
RF_IO	10	18	9	WL RF signal	

#### 1.6.3. CHIP EN

Table 1-6 CHIP EN

Symbol	Туре	QFN68	QFN32	Description
CHIP_EN	1	21	12	Enable chip. 1: enable chip, 0: shutdown chip

### 1.6.4. Power Pins

Table 1-7 Power Pins

Symbol	Туре	QFN68	QFN32	Description
VA33_XTAL	Р	11	3	3.3V for Crystal Oscillator
VA12_XTAL	Р	10	NA	1.2V for Crystal Oscillator
VR33_SYN	Р	16	6	3.3V for RF Synthesizer
VR12_SYN	Р	14	NA	1.2V for RF Synthesizer
VR33_PA	Р	17	8	3.3V for RF Power amplifier
VR33_PAD	Р	19	10	3.3V for RF
VR33_TR	Р	NA	11	3.3V for RF
VR12_TR	Р	20	NA	1.2V for RF
VD12_CORE	P	26	15	1.2V for digital core power
VD1833_FLASH	Р	50	24	3.3V/1.8V for Flash IO power
VD33_LDO	Р	NA	25	Linear Regulator input from 3.3V to 1.2V
VD33_SPS	Р	51	NA	Switching/Linear Regulator input from 3.3V to 1.2V
VD12_OUT	Р	NA	26	1.2V output from Linear Regulator
SW_LX	Р	52	NA	1.2V output from Switching/Linear Regulator
GND_SPS	Р	53	NA	Ground for Switching/Linear Regulator

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VA33_USB	Р	39	NA	3.3V power for USB Analog
VA12_USB	Р	42	NA	1.2V power for USB Analog

#### 1.6.5. XTAL Pins

Table 1-8 XTAL Pins

Symbol	Туре	QFN68	QFN32	Description X
XI	I	13	5	40MHz OSC Input Input of 40MHz Crystal Clock Reference
хо	0	12	4	Output of 40MHz Crystal Clock Reference

### 1.6.6. ADC Pins

Table 1-9 ADC Pins

Symbol	Туре	QFN68	QFN32	Description
ADC_1	I	61	NA	ADC input pin, 3.3V tolerance
VBAT_MEAS	1	57	27	ADC input pin, 5V tolerance
ADC_3		62	NA	ADC input pin, 3.3V tolerance

# 1.6.7. USB Pins

Table 1-10 USB Pins

Symbol	Туре	QFN68	QFN32	Description
USB_DP	1/0	41	NA	USB differential bus
USB_DM	/0	40	NA	USB differential bus
USB_RREF	I	43	NA	External reference resistor for USB Analog, 1% accuracy

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#### 1.6.8. **GPIO Pins**

Table 1-11 Ameba-Z GPIO

Symbol	Туре	QFN68	QFN32	RTL8710BL-QFN32	Description
GPIOA_14	I/O	22	13	13	PWM0
					SWD_CLK
GPIOA_15	I/O	23	14	14	PWM1
					SWD_DATA
GPIOA_13	I/O	24	NA	NA	PWM4
GPIOA_0	I/O	27	16	NA NA	PWM2
					EXT_32K
					WL_LED
GPIOA_16	I/O	28	NA	NA	UART2_Log_RXD
					PWM1
				X	RTC_OUT
GPIOA_17	I/O	29	NA	NA	UART2_Log_TXD
				.0	PWM2
GPIOA_25	I/O	30	NA	NA	UART1_RXD
GPIOA_26	1/0	31	NA	NA	UART1_TXD
GPIOA_28	I/O	32	NA	NA	I2C1_SCL
GPIOA_27	I/O	33	NA	NA	I2C1_SDA
GPIOA_12	I/O	34	17	NA	PWM3
GPIOA_4	I/O	35	NA	NA	UARTO_TXD
		<b>O</b>			SPI1_MOSI
	01			/	SPI0_MOSI
_					12C0_SDA
GPIOA_1	1/0	36	NA	NA	UARTO_RXD
					SPI1_CLK
					SPIO_SCK
					12C0_SCL
GPIOA_2	I/O	37	NA	NA	UARTO_CTS



					SPI1_CS
					SPIO_CS
					I2C1_SDA
GPIOA_3	1/0	38	NA	NA	UARTO_RTS
					SPI1_MISO SPS_LDO_SEL
				C	SPI0_MISO
				×	I2C1_SCL
GPIOA_6	1/0	44	18	18	SPIC_CS
					SD_D2
GPIOA_7	1/0	45	19	19	SPIC_DATA1
			(		SD_D3
GPIOA_8	1/0	46	20	NA	SPIC_DATA2
			0		SD_CMD
GPIOA_9	1/0	47	21	21	SPIC_DATA0
					SD_CLK
GPIOA_10	1/0	48	22	22	SPIC_CLK
		$\mathcal{C}$			SD_D0
GPIOA_11	1/0	49	23	NA	SPIC_DATA3
					SD_D1
GPIOA_5	1/0	59	28	NA	SDIO_SIDEBAND_INT
20101 10	1/0	50	20		PWM4
GPIOA_18	I/O	60	29	29	UARTO_RXD
				*	SPI1_CLK
					SPIO_SCK
/\(C	O				I2C1_SCL SD_D2
					TIMER4_TRIG
					I2S_MCK
GPIOA_19	I/O	61	30	NA	UARTO_CTS
	,, =		(		SPI1_CS
					SPIO_CS



SD_D3 TIMER5_TRIG	
I2S_SD_TX	
GPIOA_20         I/O         62         NA         NA         SD_CMD	
12S_SD_RX	
GPIOA_21         I/O         63         NA         NA         SD_CLK	
PWM3	
12S_CLK	
GPIOA_22         I/O         64         31         NA         UARTO_RTS	
SPI1_MISO	
SPI0_MISO	
12C0_SCL	
SD_D0	
PWM5	
12S_WS	
GPIOA_23         I/O         64         32         32         UARTO_TXD	
SPI1_MOSI	√ · · · · · · · · · · · · · · · · · · ·
SPI0_MOSI	
12C1_SDA	
SD_D1	
румо	
GPIOB_1         I/O         67         NA         NA         SPI1_CLK	
SPIO_SCK	
GPIOB_0	
SPIO_CS	
GPIOB_2 I/O 1 NA NA SPI1_MISO	
SPI0_MISO	
GPIOB_3 I/O 2 NA NA SPI1_MOSI	
SPI0_MOSI	
GPIOB_4 I/O 3 NA NA SWD_CLK	



					I2S_MCK
					_
GPIOB_5	1/0	4	NA	NA	SWD_DATA
01100_5	., 0	7	147.	107	3WD_D/(I//
					ISC CD TV
					I2S_SD_TX
GPIOA_24	1/0	5	NA	NA	I2S_SD_RX
GPIOA_31	1/0	6	NA	NA	I2S_CLK
_					
GPIOB_6	1/0	7	NA	NA	12S_WS
_	· ·				_
GPIOA_30	1/0	8	1	1	UART2_Log_TXD
0/10/1_50	1,0		_	1	0711112_E08_1710
					I2CO_SDA
					12C0_3DA
					5110.50
					PWM3
				• ()	
					RTC_OUT
			•		
GPIOA_29	1/0	9	2	2	UART2_Log_RXD
					12C0_SCL
					_
			AV		PWM4



### 2. Block Diagram

### 2.1. Functional Block Diagram

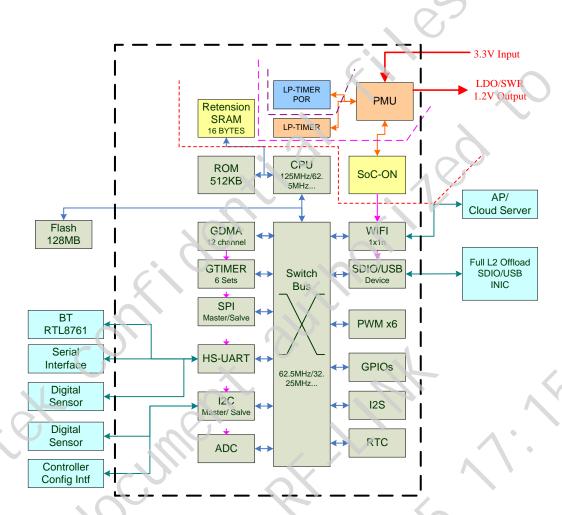


Figure 5 Block Diagram



### 2.2. WIFI Application Diagram

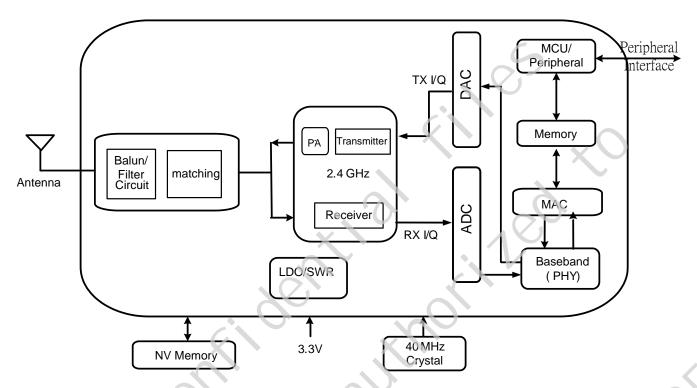


Figure 6 Single-Band 11n (1x1) Solution



### 2.3. Power Supply Application Diagram

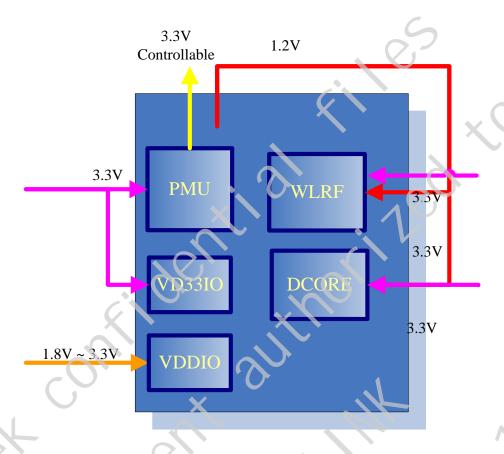


Figure 7 Power Supply Architecture

The integrated Power Management Unit (PMU) provides the following features:

- 1.2V LDO/SWR(Switching Regulator)
- 3.3V power source integrated power cut controlled by FW.



### 3. Memory organization

### 3.1. Introduction

Program memory, data memory, registers and I/O ports are organized within the same linear 4-Gbyte address space.

Ameba-Z integrates ROM, internal SRAM, NOR flash controller to provide applications with a variety of memory requirements.

The bytes are coded in memory in Little Endian format. The lowest numbered byte in a word is considered the word's least significant byte and the highest numbered byte the most significant.

All the memory areas that are not allocated to on-chip memories and peripherals are considered "Reserved". For the detailed mapping of available memory and register areas, please refer to the Memory map and register boundary addresses chapter and peripheral chapters.

### 3.2. Memory map and register boundary addresses

Table 3-1 Ameba-Z memory map

Name	Physical address	size	IP function
ROM	0x0000_0000~0x0007_FFFF	512KB	Internal ROM memory
SRAM	0x1000_0000~0x1001_FFFF	256KB	Internal SRAM memory
FLASH	0x0800_0000~0x0FFF_FFFF	128MB	External Flash memory
SYSON	0x4000_0000~0x4000_0FFF	4KB	SYS Control
GPIO	0x4000_1000~0x4000_17FF	2KB	GPIC Control
Timer	0x4000_2000~0x4000_2FFF	4KB	Timer Control
LOGUART	0x4000_3000~0x4000_33FF	1KB	UART for Log
RTC	0x4000_3400~0x4000_37FF	1KB	RTC control
Cache	0x4000_3C00^0x4000_4FFF	1KB	Flash cache control
ADC	0×4001_0000~0x4001_0FFF	4КВ	ADC control
SPIC	0x4002_0000~0x4002_0FFF	4KB	SPI flash controller
UARTO	0x4004_0000~0x4004_03FF	1KB	UARTO control
UART1	0x4004_0400~0x4004_07FF	1KB	UART1 control
SPI0	0x4004_2000~0x4004_23FF	1KB	SPI0 control
SPI1	0x4004_2400~0x4004_27FF	1KB	SPI1 control
12C0	0x4004_4000~0x4004_43FF	1KB	I2C0 control
I2C1	0x4004_4400~0x4004_47FF	1KB	I2C1 control
SDIO	0x4005_0000~0x4005_3FFF	16KB	SDIO device control

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GDMA0	0x4006_0000~0x4006_07FF	2KB	GDMA0 control
GDMA1	0x4006_1000~0x4006_17FF	2KB	GDMA1 control
125	0x4006_2000~0x4006_23FF	1KB	I2S control
IPSEC	0x4007_0000~0x4007_3FFF	16KB	Security control
WIFI	0x4008_0000~0x400B_FFFF	256KB	WIFI register
USB SIE	0x400C_0000~0x400C_0FFF	4KB	USB SIE control
USOC	0x400C_2000~0x400C_2FFF	4KB	USB device register

#### 3.3. Internal ROM

512KB ROM is integrated to provide high access speed, low leakage memory. The ROM memory clock speed is up to 125MHz. The ROM lib provides the following functions:

- Boot Code and MCU initialization
- Peripheral Drivers & API
- Non-flash booting functions and drivers
- Security function libs

### 3.4. Internal SRAM

Max. 256KB SRAM is integrated to provide instruction, data, and buffer usage. The maximum clock speed is up to 125MHz.

#### 3.5. External SPI NOR Flash

#### 3.5.1 Features

- SPI baud rate:
  - 100/83/71/62/50MHz...
- Execute in place (XIP):
  - we supports a memory-mapped I/O interface for read operation
  - Support 32K I/D read cache, 2-way associative
  - Support decryption on the fly
- SPI mode:
  - SPI/Dual SPI/DIO SPI/Quad SPI/QIO SPI
- Flash size
  - Support up to 128M Bytes flash size



### 3.5.2. Supported NOR Flash List

Table 3-2 Flash supported

Vendor	Part Number	Density	Voltage	10	Max Clock
MXIC	MX25L1633E	2MB	3.3V	41/0	85MHz
MXIC	MX25L3236F	4MB	3.3V	41/0	104MHz(6 dummy cycle)
			<b>x</b>		133MHz(10 dummy cycle)
MXIC	MX25L6433F	8MB	3.3V	41/0	80MHz (6 dummy cycle)
					133MHz (10 dummy cycle)
MXIC	MX25L12845G	16MB	3.3V	41/0	70MHz
MXIC	MX25L1606E	2MB	3.3V	20	80MHz
MXIC	MX25V8006E	1MB	3.3V	20	70MHz
MXIC	MX25V1635F	2MB	3.3V	41/0	80MHz
MXIC	MX25V8035F	1MB	3.3V	41/0	104MHz
MXIC	KH25L8006EM2I-12G	1MB	3.3V	20	80MHz
MXIC	KH25L1606EM2I-12G	2MB	3.3V	20	80MHz
MXIC	MX25R1635FM1IH0	2MB	1.8/3.3V	41/0	80MHz
Winbond	W25Q80DV	1MB	3.3V	41/0	104MHz
Winbond	W25Q16DV	2MB	3.3V	41/0	104MHz
Winbond	W25Q32FV	4MB	3.3V	41/0	104MHz
Winbond	W25R64FV	8MB	3.3V	41/0	104MHz
Winbond	W25R128FV	16MB	3.3V	41/0	104MHz
Micron	N25Q032A13ESE40E	4MB	3.3V	41/0	108MHz
Micron	N25Q064A13ESED0E	8MB	3.3V	41/0	108MHz
Micron	N25Q128A	16MB	3.3V	41/0	108MHz
Micron	N25Q00AA13GSF40F	128MB	3.3V	41/0	108MHz
Gigadevice	GD25Q80C	1MB	3.3V	41/0	120MHz
Gigadevice	GD25Q16C	2MB	3.3V	41/0	120MHz
Gigadevice	GD25Q32C	4MB	3.3V	41/0	120MHz
Gigadevice	GD25Q64C	8MB	3.3V	41/0	120MHz
Gigadevice	GD25Q128C	16MB	3.3V	41/0	80MHz



HuaHong	BH25D80A	2MB	3.3V	20	108MHz
ESMT	EN25QH16A	2MB	3.3V	41/0	104MHz
ESMT	EN25QH16B-104HIP2A	2MB	3.3V	41/0	104MHz
ESMT	EN25Q80B	1MB	3.3V	41/0	104MHz
FM	FM25Q08A	2MB	3.3V	41/0	104MHz

### 3.5.3. Electrical Specifications

Table 3-3 Flash Bus DC Parameters

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	Notes
V <sub>IH</sub>	Input-High Voltage	LVTTL	2.0	-	-	V	1
V <sub>IL</sub>	Input-Low Voltage	LVTTL	-	-	0.8	V	2
V <sub>OH</sub>	Output-High Voltage	-	2.4	<b>D</b> -	-	V	3
V <sub>OL</sub>	Output-Low Voltage	-		-	0.4	V	3
I <sub>IL</sub>	Input-Leakage Current	V <sub>IN</sub> =3.3V or 0	-10	±1	10	μА	-
I <sub>OZ</sub>	Tri-State Output-Leakage Current	- 0	-10	±1	10	μА	-
R <sub>PU</sub>	Input Pull-Up Resistance	- 0	-	75	-	ΚΩ	4
R <sub>PD</sub>	Input Pull-Down Resistance	-	-	75	-	ΚΩ	4

Note 1:  $V_{IH}$  overshoot: VIH (MAX)=VDDH + 2V for a pulse width  $\leq$ 3ns.

Note 2:  $V_{IL}$  undershoot:  $V_{IL(MIN)}=2V$  for a pulse width  $\leq 3$  ns.

Note 3: The output current buffer is 8mA for the flash address and data bus; and is 8mA for Flash control signals.

Note 4: These values are typical values checked in the manufacturing process and are not tested.



# 4. Exception table

Table 4-1 Exception table

Exception Number	Exception Type	Description
	Reset	Reset
	NMI	Nonmaskable interrupt (external NMI input). The WDG is linked to the NMI vector
	Hard Fault	All fault conditions if the corresponding fault handler is not enabled
	MemManager Fault	Memory management fault; Memory Protection Unit (MPU) violation or access to illegal locations
	Bus Fault	Bus error; occurs when Advanced High-Performance Bus (AHB) interface receives an error response from a bus slave (also called prefetch abort if it is an instruction fetch or data abort if it is a data access)
	Usage Fault	Exceptions resulting from program error or trying to access coprocessor (the Cortex-M4 does not support a coprocessor)
	RSVD	
	SVC	Supervisor Call
	Debug Monitor	Debug monitor (breakpoints, watchpoints, or external debug requests)
	RSVD	-
	PendSV	Pendable Service Call
	SYSTICK	System Tick Timer
[0]	System_ISR	X IL
[1]	WDG	Watch dog global insterrupt
[2]	Timer0	Timer0 global interrupt
[3]	Timer1	Timer1 global interrupt
[4]	Timer2	Timer2 global interrupt
[5]	Timer3	Timer3 global interrupt
[6]	SPI0	SPIO global interrupt for communication spi
[7]	GPIO	GPIO portA global interrupt
[8]	UARTO	UARTO global interrupt
[9]	SPI_FLASH	SPI Flash global interrupt
[10]	UART1	UART1 global interrupt
[11]	Timer4	Timer4 global interrupt
[12]	SDIO_Dev	SDIO device global interrupt
[13]	12S0	I2SO global interrupt
[14]	Timer5	Timer5 global interrupt
[15]	WL_DMA	Wlan Host global interrupt
[16]	WL_PROTOCOL	Wlan Firmware Wlan global interrupt
L		



[17]	CRYPTO	IPsec global interrupt
[18]	SPI1	SPI1 global interrupt for communication spi
[19]	Peripheral_ISR	See Below Table
[20]	GDMA0_Channel0	GDMA0 channel 0 global interrupt
[21]	GDMA0_Channel1	GDMA0 channel 1 global interrupt
[22]	GDMA0_Channel2	GDMA0 channel 2 global interrupt
[23]	GDMA0_Channel3	GDMA0 channel 3 global interrupt
[24]	GDMA0_Channel4	GDMA0 channel 4 global interrupt
[25]	GDMA0_Channel5	GDMA0 channel 5 global interrupt
[26]	I2C0	I2CO global interrupt
[27]	I2C1	I2C1 global interrupt
[28]	uart log	log uart intr
[29]	adc	adc intr
[30]	rdp_int	cpu rdp protection int
[31]	rtc_int	rtc timer int
[32]	GDMA1_CHANNELO_IRQ	GDMA1 channel 0 global interrupt
[33]	GDMA1_CHANNEL1_IRQ	GDMA1 channel 1 global interrupt
[34]	GDMA1_CHANNEL2_IRQ	GDMA1 channel 2 global interrupt
[35]	GDMA1_CHANNEL3_IRQ	GDMA1 channel 3 global interrupt
[36]	GDMA1_CHANNEL4_IRQ	GDMA1 channel 4 global interrupt
[37]	GDMA1_CHANNEL5_IRQ	GDMA1 channel 5 global interrupt
[38]	USB_IRQ	USOC interrupt
[39]	RXI300_IRQ	
[40]	USB_SIE	USB SIE interrupt



### 5. Pinmux Alternate Functions

**Table 5-1 Pinmux Alternate Function mapping** 

						1							ı
QFN68	QFN32	8710BL QFN32	GP10	UART	SPI Master	SPI Slave	SPI Flash	12C	SDIO	PWM/TI MER	EXT32K	12S	Others
~	<b>√</b>	<b>✓</b>	PA_14							PWM0	SWD_CLK		
/	1	1	PA_15							PWM1	SWD_DAT		
1			PA_13							PWM4	$\mathbf{x}^{\mathbf{C}}$		
1	✓		PA_0							PWM2	ext_32K		
1			PA_16	UART2_log_R XD			<b>7</b>			PWM1	RTC_OUT		
1			PA_17	UART2_log_T XD		X			1	PWM2			
1			PA_25	UART1_RXD									
/			PA_26	UART1_TXD	S								
1			PA_28		<b>O</b>		NC.	12C1_8CL					
1			PA_27					I2C1_SDA					
-	*		PA_12				<b>)</b>			PWM3			5
1			PA_4	UART0_TXD	SPI1_MOS I	SPI0_MOS I	<b>)</b>	I2C0_SDA	1				
*			PA_1	UART0_RXD	SPI1_CLK	SPI0_SCK		I2C0_SCL				<u>( · · · · · · · · · · · · · · · · · · ·</u>	•
1		<b>&gt;</b>	PA_2	UART0_CTS	SPI1_CS	SPI0_CS		I2C1_SDA			^		
1	X	0	PA_3	UARTO_RTS	SPI1_MIS O	SPI0_MIS O		I2C1_SCL			•		
1	<u> </u>	*	PA_6				SPIC_CS		SD_D2		1		
· (	<i>y</i>	*	PA_7				SPIC_DATA1		SD_D3				
	✓		PA_8	)			SPIC_DATA2		SD_CMD				
>	✓	*	PA_9				SPIC_DATA0		SD_CLK				
-	1	NO.	PA_10				SPIC_CLK		SD_D0				
1	1		PA_11				SPIC_DATA3		SD_D1				
/	*		PA_5				$\wedge$		SDIO_SID EBAND_IN T	PWM4			WAKEUP_ 1
1	*	<b>✓</b>	PA_18	UART0_RXD	SPI1_CLK	SPI0_SCK		I2C1_SCL	SD_D2	TIMER4 _TRIG		I2S_MCK	WAKEUP_ 0
~	*		PA_19	UARTO_CTS	SPI1_CS	SPI0_CS		I2C0_SDA	SD_D3	TIMER5 _TRIG		I2S_SD_TX	ADC1 (QFN32 Not Support)
1			PA_20						SD_CMD			I2S_SD_RX	ADC3



/			PA_21						SD_CLK	PWM3		I2S_CLK	
1	·		PA_22	UARTO_RTS	SPI1_MIS O	SPI0_MIS O		I2C0_SCL	SD_D0	PWM5		I2S_WS	WAKEUP_ 2
~	~	<b>*</b>	PA_23	UARTO_TXD	SPI1_MOS I	SPI0_MOS I		I2C1_SDA	SD_D1	PWM0			WAKEUP_ 3
-			PB_1		SPI1_CLK	SPI0_SCK			01				
/			PB_0		SPI1_CS	SPI0_CS							
~			PB_2		SPI1_MIS O	SPI0_MIS O							
~			PB_3		SPI1_MOS I	SPI0_MOS I							
~			PB_4							A	SWD_CLK	I2S_MCK	
~			PB_5				, O		C		SWD_DAT A	I2S_SD_TX	
~			PA_24			X			1			I2S_SD_RX	
/			PA_31									I2S_CLK	
~			PB_6		A							I2S_WS	
1	*	4	PA_30	UART2_log_T XD			~\C	I2C0_SDA		PWM3	RTC_OUT		
~	<b>✓</b>	·	PA_29	UART2_log_R XD				I2C0_SCL		PWM4			



### 6. PMU

### 6.1. Features

### 6.2. Power Mode and Power Consumption

Table 6-1 Power Mode Brief Summary and Typical Power Consumption and Resume Time

Power Mode	Power Consumption		X
	ТурісаІ	Maximum	Units
Deep Sleep Mode	7	3	uA
Deep Standby Mode	70	70	uA
Sleep Power Gate	120	120	uA
Sleep Clock Gate	350	350	uA

### 6.3. Shutdown Mode

• CHIP\_EN deasserts to shutdown whole chip without external power cut components required.

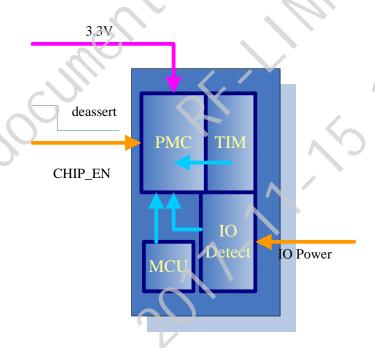


Figure 8 Shutdown Mode



# 6.4. Deep Sleep Mode

• CHIP\_EN keeps high. Enter into Deep Sleep mode by API.

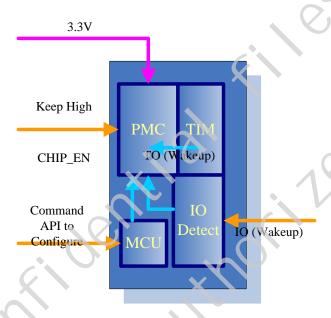


Figure 9 Deep Sleep Mode

## 6.4.1. Power Domain

Table 6-2 Deep Sleep Mode Power Domain

Functions	Power State	Comment
cortex-M4 core	OFF	\ \ \
system clock	OFF	
SRAM	OFF	
Regulator	OFF	
Peripherals	OFF	
Backup register	OFF	
RTC	OFF	
low precision timer	ON	1
Dsleep wake pin	ON	4



## 6.4.2. Wakeup Source

**Table 6-3 Deep Sleep Wakeup Source** 

Wakeup source	Wakeup	Comment
low precision timer	YES	10
Dsleep Wake pin	YES	GPIOA_5 GPIOA_18
		GPIOA_22
		GPIOA_23

# 6.5. Deep Standby Mode

• CHIP\_EN keeps high. Entering into Deep Sleep mode by API.

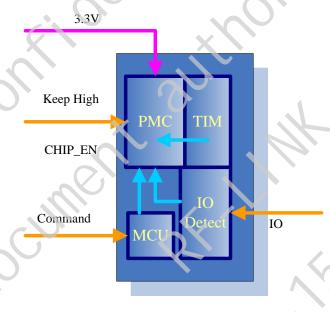


Figure 10 Deep Standby Mode

## 6.5.1. Power Domain

Table 6-4 Deep Standby Power Domain

functions	Power State	comment
cortex-M4 core	OFF	
system clock	OFF	

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SRAM	OFF	
Regulator	OFF	
Peripherals	OFF	
Backup register	ON	16B
RTC	ON	
System timer	ON	1
low precision timer	ON	1
wake pin	ON	4

## 6.5.2. Wakeup Source

**Table 6-5 Deep Standby Wakeup Source** 

Wakeup source	Wakeup	Comment
Wake pin	YES	GPIOA_5
		GPIOA_18
		GPIOA_22
		GPIOA_23
RTC	YES	1
System timer	YES	. 1911
low precision timer	YES	

## 6.6 Sleep Power Gate

### 6.6.1. Power Domain

Sleep mode turn off power domain including cortex-M4 core, and system clock. System is not required to restart after wakeup.

## 6.6.2. Wakeup source

**Table 6-6 Sleep Power Gate Wakeup Source** 

Wakeup source	Wakeup	comment
GPIO interrupt	YES	High/Low active
general purpose timer	YES	



wlan	YES	
ADC	YES	
UART	YES	_
12C	YES	0.2
SDIO/GSPI	YES	
USB	YES	
Wake pin	YES	GPIOA_5
		GPIOA_18
		GPIOA_22
		GPIOA_23
RTC	YES	•. /
System timer	YES	
low precision timer	YES	0,

# 6.7. Sleep Clock Gate

### 6.7.1. Power Domain

Sleep mode turn off system clock. System is not required to restart after wakeup.

## 6.7.2. Wakeup source

Table 6-7 Sleep Clock Gate Wakeup Source

Wakeup source	Wakeup	comment
GPIO interrupt	YES	High/Low active
general purpose timer	YES	
wian	YES	
ADC	YES	
UART	YES	
12C	YES	
SDIO/GSPI	YES	
USB	YES	



Wake pin	YES	GPIOA_5
		GPIOA_18
		GPIOA_22
		GPIOA_23
RTC	YES	
System timer	YES	
low precision timer	YES	\ \ \ \ \ \



## 7. Firmware Protection

## 7.1. Trust-Zone Lite

- Top 4k RAM cannot be read.
- RDP Interrupt will happen when invalid access happen.
- RDP image should be encrypted use RDP KEY,
- RDP image can only be decrypted and load to RDP RAM use IPSEC.
- KEY
  - 16B RDP key should be written to EFUSE RDP key area
  - Hidden EFUSE 0xB0~0xBF
  - Cannot read back again. (HW protect)
  - Auto-load to IPSEC when boot.
- Enable
  - Hidden EFUSE 0xC0[0].
  - Cannot be closed after open.



### 8. WIFI

### 8.1. General

- CMOS MAC, Baseband PHY, and RF in a single chip for 802.11b/g/n compatible WLAN
- Complete 802.11n solution for 2.4GHz band
- 72.2Mbps receive PHY rate and 72.2Mbps transmit PHY rate using 20MHz bandwidth
- 150Mbps receive PHY rate and 150Mbps transmit PHY rate using 40MHz bandwidth
- Compatible with 802.11n specification
- Backward compatible with 802.11b/g devices while operating in 802.11n mode

## 8.2. Standards Supported

- 802.11b/g/n compatible WLAN
- 802.11e QoS Enhancement (WMM)
- 802.11i (WPA, WPA2). Open, shared key, and pair-wise key authentication services
- WIFI WPS support
- WIFI Direct support
- Light Weight TCP/IP protocol

## 8.3. WLAN MAC Features

- Frame aggregation for increased MAC efficiency (A-MSDU, A-MPDU)
- Low latency immediate High-Throughput Block Acknowledgement (HT-BA)
- Long NAV for media reservation with CF-End for NAV release
- PHY-level spoofing to enhance legacy compatibility
- Power saving mechanism



## 8.4. WLAN PHY Features

- 802.11n OFDM
- One Transmit and one Receive path (1T1R)
- 20MHz and 40MHz bandwidth transmission
- Short Guard Interval (400ns)
- DSSS with DBPSK and DQPSK, CCK modulation with long and short preamble
- OFDM with BPSK, QPSK, 16QAM, and 640QAM modulation. Convolutional Coding Rate: 1/2, 2/3, 3/4, and 5/6
- Maximum data rate 54Mbps in 802.11g and 150Mbps in 802.11n
- Fast receiver Automatic Gain Control (AGC)



## 9. Basic timer

## 9.1. Introduction

The basic timers TIM0/TIM1/TIM2/TIM3 consist of a 32-bit auto-reload counter without prescaler.

They may be used as generic timers for time-base generation.

Table 9-1 Basic timer features

Name	TIM0/1/2/3
channels	1
clock source	32k
resolution	32bit
prescaler	8bit
counter mode	Up
one puise mode	-
FWIN mode with polarity selection	-
statistic pulse width	11
statistic pulse number	
interrupt generation	•
DMA generation	-
input pin	-
output pin	- (_



# 10. Capture timer

## 10.1. Introduction

The Capture timer (TIM4) consists of a 16-bit auto-reload counter driven by a 8-bit programmable prescaler.

It may be used for a variety of purposes, including measuring the pulse lengths or numbers of input signals.

Table 10-1 Capture timer features

Name	TIM4
channels	1
clock source	XTAL
resolution	16bit
prescaler	8bit
counter mode	Up
one pulse mode	-
PWM mode with polarity selection	-
statistic pulse width	-11
statistic pulse number	. 19.
interrupt generation	•
DMA generation	9
input pin	1 input capture
output pin	- <_



### 11. PWM timer

## 11.1. Introduction

The PWM timer (TIM5) consists of a 16-bit auto-reload counter driven by a 8-bit programmable prescaler.

It may be used for a variety of purposes, including measuring the pulse lengths of input signals (input capture) or generating output waveforms (PWM).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler.

### 11.2. Features

Table 11-1 PWM timer features

Name	TIM5
channels	6
clock source	XTAL
resolution	16bit
prescaler	8bit
counter mode	Up
one puise mode	•
PWM mode with polarity selection	
statistic pulse width	
statistic pulse number	7
interrupt generation	•
DMA generation	•
input pin	1 input capture
output pin	6 PWM out

# 11.3. Function description

### 11.3.1. PWM mode

Pulse Width Modulation mode allows you to generate a signal with a frequency determined by the value of the TIMx\_ARR register and a duty cycle determined by the value of the CCRx field of TIMx\_CCRx register.

Period: =  $(ARR + 1) * T_{CNT}$ 

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Duty cycle: 
$$D_{PWM} = \frac{(CCRx+1)*T_{CNT}}{T_{PWM}}$$

Where 
$$T_{CNT} = T_{XTAL} * (PSC + 1)$$

The PWM mode can be selected independently on each channel (one PWM per OCx output) by setting '0' in the OCxM bits in the TIMx\_CCRx register. You must enable the corresponding preload register by setting the OCxPE bit in the TIMx\_CCRx register, and eventually the auto-reload preload register by setting the ARPE bit in the TIMx\_CR register.

As the preload registers are transferred to the shadow registers only when an update event occurs, before starting the counter, you have to initialize all the registers by setting the UG bit in the TIMx\_EGR register.

OCx polarity is software programmable using the CCxP bit in the TIMx\_CCRx register. It can be programmed as active high or active low.

In PWM mode, TIMx\_CNT and CCRx (in TIMx\_CCRx) are always compared to determine whether TIMx\_CNT  $\leq$  CCRx (in TIMx\_CCRx). The PWM signal OCx is active as long as TIMx\_CNT  $\leq$  CCRx (in TIMx\_CCRx), otherwise it becomes inactive.

The timer is only able to generate PWM in edge-aligned mode.



### **12.** RTC

### 12.1. Introduction

The real-time clock (RTC) is an independent BCD timer/counter.

One 32-bit registers contain the seconds, minutes, hours (12 or 24-hour format) expressed in binary coded decimal format (BCD).

One 32-bit registers contain the days expressed in binary format.

Daylight saving time compensation can also be performed.

Additional two 32-bit registers contain the programmable alarm seconds, minutes, hours and days.

A digital calibration feature is available to compensate for some deviation.

After backup domain reset, all RTC registers are protected against possible parasitic write accesses.

As long as the supply voltage remains in the operating range, the RTC never stops, regardless of the device status (Run mode, low power mode or under reset).

### 12.2. Features

- Time with seconds, minutes, hours, days (12 or 24-hour format).
- Daylight saving compensation programmable by software.
- One programmable alarm with interrupt function. The alarms can be triggered by any combination of the time fields.
- Maskable interrupts/events.
  - - Alarm
- Digital calibration circuit
- Register write protection

## 12.3. Clock and Prescalers

A programmable prescaler stage generates a 1 Hz clock which is used to update the calendar. To minimize power consumption, the prescaler is split into 2 programmable prescalers.

A 9-bit asynchronous prescaler configured through the PREDIV\_A bits of the RTC\_PRER register.

A 9-bit synchronous prescaler configured through the PREDIV\_S bits of the RTC\_PRER register.

Note: It is recommended to configure the asynchronous prescaler to a high value to minimize consumption.

Default, the asynchronous prescaler division factor is set to 128, and the synchronous division factor to 256, to obtain an internal clock frequency of 1 Hz (ck\_spre) with 32.768 kHz as RTCLCK

 $f_{clk}$  apre is given by the following formula:

$$f_{clk\_apre} = \frac{f_{RTCCLK}}{PREDIV\_A + 1}$$



 $f_{\text{clk\_spre}}$  is given by the following formula:

$$f_{clk\_spre} = \frac{f_{clk\_apre}}{PREDIV\_S + 1}$$

## 12.4. RTC Reset

	RTC Reset	RTC Wakeup
Power Off	Υ	N/A
Hardware Reset	Υ	N/A
Deep Sleep	Υ	N/A
Deep Standby	N	Y
Sleep	N	Y
System Reset	N	N/A
Vector Reset	N	N/A



# 13. BACKUP Register

## 13.1. Introduction

The backup register are 32-bits registers used store 32 bytes of user application data, Backup registers are not reset by a system, or when the device wakes up from the Standby mode.

byte0 $^{\sim}$ byte3 are reserved for system, and byte4-byte31 are reserved for user.

# 13.2. BACKUP Register API

Backup Register API	Introduction
< BKUP_Write >	■ backup register dwrod write
< BKUP_Read >	■ backup register dwrod read
< BKUP_Set >	set some bits of backup register
< BKUP_Clear >	clear some bits of backup register

# 13.3. BACKUP Register Reset

	RTC Reset
Power Off	Υ
Hardware Reset	Υ
Deep Sleep	Υ
Deep Standby	N
Sleep	N
System Reset	N
Vector Reset	N



### **14. UART**

## 14.1. Introduction

The Universal Asynchronous Receiver Transmitter (UART) module offers a flexible means of full duplex data exchange with external equipment requiring an industry standard NRZ asynchronous serial data format.

It offers a very wide range of baud rates using a fractional baud rate generator.

Low power Rx mode is implemented by monitoring Rx baud rate error and own frequency drift.

This chip integrates three UART modules:

- 2 normal UART with low power or high speed.
- 1 LOGUART with high speed.

### 14.2. Features

- Support UART format: 1 start bit, 7/8 data bits, 0/1 parity bit and 1/2 stop bit
- Support a very wide range of baud rate, 110~6Mbps.
- APB3 bus interface
- Support DMA mode
- Support auto flow control
- Support interrupt control
- Support IrDA
- Support loopback mode for test
- Differentiate clk for Tx path and Rx path
- Fractional baud rate generator for Tx path and Rx path
- Support low power Rx path without XTAL & PLL, Baud rate 110~500000.
- Monitor and eliminate Rx baud rate error and own frequency drift automatically for new Rx path
- Transmit and Receive Data FIFO
- Programmable Receive Data FIFO Trigger Level

### 14.3. Baud Rate

#### Table 14-1 UART Baud Rate

	High Rate	Low Power
clock select	40MHz XTAL	8MHz



according to the second	1200 0000	1200
supported baud	1200, 9600,	1200,
rate(bps)	14400, 19200,	9600,
	28800, 38400,	14400,
	57600, 76800,	19200,
	115200, 128000,	28800,
	153600, 230400,	38400,
	406800, 500000,	57600,
	921600, 1000000,	76800,
	1382400, 14444400,	115200,
	1500000, 1843200,	128000,
	2000000, 2100000,	153600,
	2764800, 3000000,	230400,
	3250000, 3692300,	406800,
	3750000, 4000000,	500000
	6000000	

# 14.4. UART Interface Signal Levels

The UART signal level ranges from 1.8V to 3.3V. The host provides the power source with the targeted power level to the Ameba-Z UART interface via the IO power.



## 15. SPI

## 15.1. Introduction

Ameba-Z support Motorola Serial Peripheral Interface (SPI) – A four-wire, full-duplex serial protocol from Motorola.

There are four possible combinations for the serial clock phase and polarity. The clock phase (SCPH) determines whether the serial transfer begins with the falling edge of the slave select signal or the first edge of the serial clock.

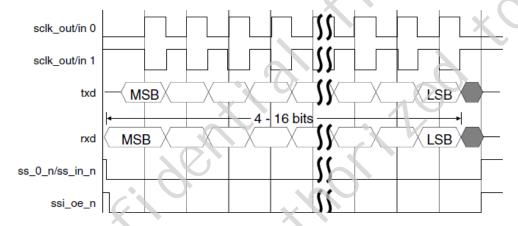


Figure 11 SPI Serial Format (SCPH = 0)

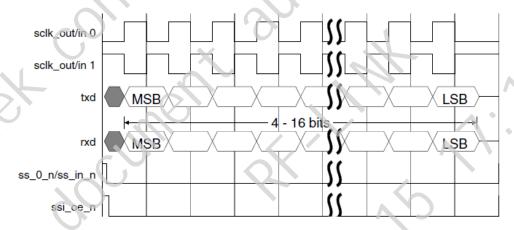
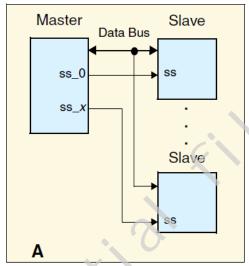


Figure 12 SPI Serial Format (SCPH = 1)

The slave select line is held high when the SPI is idle or disabled.





ss = slave select line

Figure 13 Slave Selection

- Motorola SPI Interface Operations support
- Support maximum 2 SPI port
- Support Master (SPI1 only), and Slave(SPI0 only) mode
- Support DMA to offload CPU bandwidth
- high speed SPI with baud rate up to 31.25MHz
- Programmable clock bit-rate
- Programmable clock polarity and phase
- Master just support 1 hardware CS, you can use GPIO to control more SPI salve.



### 16. I2C

### 16.1. Introduction

The I2C bus is a two-wire serial interface, consisting of a serial data line (SDA) and a serial clock (SCL).

When the bus is idle, both the SCL and SDA signals are pulled high through internal pull-up resistors. When the master wants to start a transmission on the bus, the master issues a START condition. This is defined to be a high-to-low transition of the SDA signal while SCL is 1. When the master wants to terminate the transmission, the master issues a STOP condition. This is defined to be a low-to-high transition of the SDA line while SCL is 1. When data is being transmitted on the bus, the SDA line must be stable when SCL is 1.

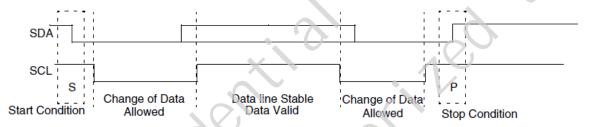


Figure 14 I2C start stop condition

I2C bus carry information between the devices connected to the bus. Each device is recognized by a unique address and can operate as either a "transmitter" or "receiver," depending on the function of the device.

Devices can also be considered as masters or slaves when performing data transfers. A master is a device that initiates a data transfer on the bus and generates the clock signals to permit that transfer. At that time, any device addressed is considered a slave.

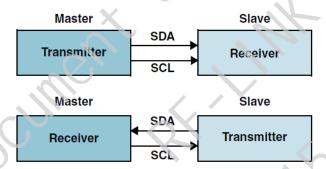


Figure 15 Master/Slave and Transmitter/Receiver Relationships

Ameba-Z can operate in standard mode (with data rates 0 to 100 Kb/s), fast mode (with data rates less than or equal to 400 Kb/s), high-speed mode (with data rates less than or equal to

#### 3.4 Mb/s) are not supported.

Ameba-Z can communicate with devices only of these modes as long as they are attached to the bus. Additionally, fast mode devices are downward compatible. For instance, fast mode devices can communicate with standard mode devices in 0 to 100 Kb/s I2C bus system. However, standard mode devices are not upward compatible and should not be incorporated in a fast-mode I2C bus system as they cannot follow the higher transfer rate and unpredictable states would occur

There are two address formats: the 7-bit address format and the 10-bit address format.

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#### 7-bit Address Format

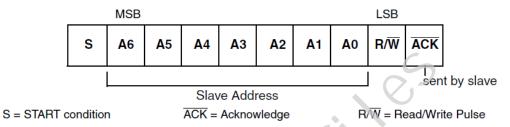


Figure 16 7-bit address format

#### 10-bit Address Format

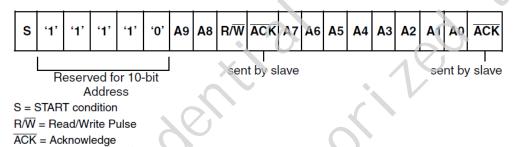


Figure 17 10-bit address format

- Support maximum 2 I2C port
- Two speeds:
  - Standard mode (0 to 100 Kb/s)
  - Fast mode (<400 Kb/s)
  - Not support High-speed mode (<3.4 Mb/s)
- Master or Slave I2C operation
- 7- or 10-bit addressing
- Transmit and receive buffers
- TX and RX DMA support
- Slave mode address match wakeup for power save



### **17.** I2S

## 17.1. Introduction

I2S(Inter IC Sound)is a standard communication structure using in digital audio systems. Since the digital audio signals in consumer audio market are being processed by a number of VLSI ICs, standardized communication structure could increase system flexibility.

### 17.2. Features

- Sample bit: 16 bit, 24 bit
- Sample rate: 8K, 16K, 24K, 32K, 48K, 96K, 7.35K, 14.7K, 22.05K, 29.4K, 44.1K, 88.2K
- IIS throughput: 0.512Mbps (16K\*32bit) ~ 6.144Mbps (96K\*64bit)
- IIS channel number: mono, stereo
- Integrated DMA engine to minimize SW efforts
- Master or slave mode support
- Support Mono and Stereo TX or RX or TX&RX mode
- Not support PCM mode

## 17.3. Function Description

## 17.3.1. Clock Type

- SCLK: 6.144MHz, 3.072MHz, 2.048Mz, 1.536MHz, 1.024MHz, 0.512MHz, 0.256MHZ
- MCLK: 24.576Mhz, 12.288Mz, 8.192MHz, 6.144MHz, 4.096Mhz, 2.048Mhz
- WS(Sample Rate): 96K, 48K, 32K, 24K, 16K, 8K ()
- MCLK=4SCLK=256WS (24bit)
- MCLK=8SCLK=256WS (16bit)



## 18. ADC

## 18.1. Introduction

Ameba-Z integrates one ADC with as many as four channels: One internal channel and three external channels.

## 18.2. Features

Item	Spec.	Description
Channel	4 independent channels	1 internal channel
	. 0	3 external channels
Input Power	0~3.3V or 0~5V	CH1 & CH3: 0~3.3V
		CH2: 0~5V
Input Signal Bandwidth	<60Hz	
Resolution	12-bits	Bit Number
DMA Mode	Support	
One Shot Mode	Support	Support Timer(TIM3) trigger one shot
		sampling without CPU active for save power
Sample Rate	Max. 1MHz per channel, Configurable	Sampling frequency
Wakeup Method	buffer threshold and event trigger	11.

# 18.3. Channel Description

20	Internal	PinName	Voltage
СНО	Υ	N/A	N/A
CH1	N	GPIOA19/ADC_1	0~3.3V
CH2	 N	VBAT_MEAS	0~5V
СНЗ	N	GPIOA_20/ADC_3	0~3.3V



### 19. GDMA

## 19.1. Introduction

General purpose direct memory access (GDMA) is used to transfer data between peripherals and memory as well as memory to memory without CPU actions.

Ameba-Z integrate two GDMA modules, One GDMA module has 6 channels to manage the data transfer between memory and peripherals.

## 19.2. Features of GDMA

- Dual port DMA with totally 12 channels
- Single FIFO per channel for source and destination
- Support memory-memory, memory-peripheral, peripheral-memory, and peripheral-peripheral DMA transfer
- Support multi block transfer
- Maximum block size is 4095
- Programmable source and destination addresses, address increment, decrement, no change or address auto-reload
- Configurable endian
- Support block level flow control
- DMA interrupt for complete or error



# 20. WGT (watchdog timer)

## 20.1. Introduction

The watchdog timer regains control in case of system failure (due to a software error) to increase application reliability. The WDT can generate a reset or an interrupt when the counter reaches a given timeout value.

- Watch dog timer is count with 32.768KHz/(divfactor+1). Dividing factor is 1~0xFFFF.
- Timeout value: 1ms ~ 8190s
- Configurable reset or interrupt generation with the given timeout value
- Watch dog timer disable/enable/refresh



### 21. **GPIO**

### 21.1. Introduction

Ameba-Z GPIO IP controls the output data and direction of external I/O pads. It also can read back the data on external pads using memory-mapped registers.

Ameba-Z support two port: PORT\_A(0~31) and PORT\_B(0~6).

Port A can be programmed to accept external signals as interrupt sources on any of the bits of the signal. The type of interrupt is programmable with one of the following settings:

- Active-high and level
- Active-low and level
- Rising edge
- Falling edge

NOTICE: Both edge interrupt is not support.

The interrupts can be masked by programming the gpio\_int\_mask register. The interrupt status can be read before masking (called raw status) and after masking.

Whenever Port A is configured for interrupts, the data direction must be set to Input. If the data direction register is reprogrammed to Output, then any pending interrupts are not lost. However, no new interrupts are generated.

If the user has configured Port A to include the interrupt feature, the GPIO can be configured to either include or exclude a debounce capability using the GPIO DEBOUNCE parameter.

The external signal can be debounced to remove any spurious glitches that are less than one period of the external debouncing clock.

## 21.2. Features of GPIO

- GPO and GPI function
- Support interrupt detection with configurable polarity per GPIO
- internal weak pull up and pull low per GPIO
- Multiplexed with other specific digital functions
- GPIO\_DEBOUNCE to remove any spurious glitches



# 22. Security Engine

## 22.1. Introduction

The Security engine provides fast and energy efficient hardware encryption and decryption service for Ameba-Z.

- Provide low SW computing and high performance encryption
- Efficient CPU/DMA access support
- Block size up to 32KB.
- Supported authentication algorithms:
  - MD5
  - SHA-1
  - SHA-2 (SHA-224 / SHA-256 )
  - HMAC-MD5
  - HMAC-SHA1
  - HMAC-SHA2
- Supported Encryption / Decryption mechanisms:
  - DES ( CBC / ECB )
  - 3DES ( CBC / ECB )
  - AES-128 (CBC / ECB / CTR)
  - AES-192 ( CBC / ECB / CTR )
  - AES-256 ( CBC / ECB / CTR )



# 23. USOC (USB device)

## 23.1. Introduction

USOC is USB device controller that is compliant with the USB 2.0 specification.

The USOC module connects SIE to AHB system bus so that USB can work in two modes:

- iNIC mode, all SIE data transfer is through AHB bus.
- NIC mode or Dongle mode, all SIE data transfer is through legacy TDE/RDE interface.

In two modes, register access path are all enabled to get the highest flexibility to configure SIE, or other system block such as WLON/SYSON.

- Support USB 2.0
- Support HS/FS/LS mode
- Internal DMA support, DMA works based on register settings
- Support high performance Ethernet to WIFI transformation
- Support non-flash booting in the use if Ethernet to WIFI transformation card
- 1.5KByte bulk-in buffer and 1.5KByte bulk-out buffer
- Switch NIC and iNIC mode by register settings
- Interrupt mitigation
- Error handling
- Support Mass storage and network device



# 24. SDIO/GSPI device

## 24.1. Introduction

The SDIO Controller supports the Secure Digital I/O communication protocol and Realtek SPI protocol.

### 24.2. Features

- Support SDIO 2.0 SDR25
- CIS can be configured with internal non-volatile memory for fast card detection
- Realtek SPI provides high efficiency SPI interface with interrupt and full duplex mode
- Support high performance Ethernet to WIFI transformation
- Support non-flash booting in the use if Ethernet to WIFI transformation card
- Clock rate variable up to 50 MHz
- Internal DMA support

# 24.3. Bus Timing Specification

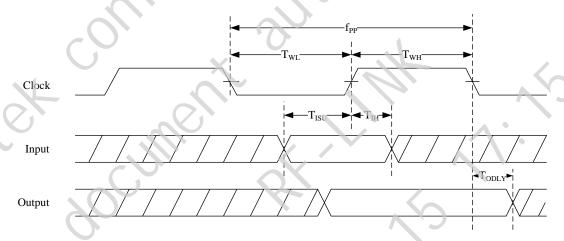


Figure 18 SDIO bus timing

**Table 24-1 SDIO Interface Timing Parameters** 

NO	Parameter	<b>A A</b>	Mode	MIN	MAX	Unit
$f_{PP}$	Clock Frequency		Default	0	25	MHz
			HS	0	50	MHz
T <sub>WL</sub>	Clock Low Time	70	DEF	10	-	ns
			HS	7	-	ns

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T <sub>WH</sub>	Clock High Time	DEF	10	-	ns
		HS	7	-	ns
T <sub>ISU</sub>	Input Setup Time	DEF	5	-	ns
		HS	6	-	ns
T <sub>IH</sub>	Input Hold Time	DEF	5	-	ns
		HS	2	-	ns
T <sub>ODLY</sub>	Output Delay Time	DEF	-	14	ns
		HS	-	14	ns





## 25. Electrical Characteristics

## 25.1. Temperature Limit Ratings

**Table 25-1 Temperature Limit Ratings** 

Parameter	Minimum	Maximum	Units
Storage Temperature	-55	+125	°C
Ambient Operating Temperature	-20	+85	°C
Junction Temperature	0	+125	°C

## 25.2. Power Supply DC Characteristics

**Table 25-2 Power Supply DC Characteristics** 

Symbol	Parameter	Minimum	Typical	Maximum	Units
VA33, VD3310,	3.3V Supply Voltage	3.0	3.3	3.6	V
SW_HV3		X			
VDD_IO	Digital IO Supply Voltage	1.62	1.8~3.3	3.6	V
VA12_AFE,	1.2V Core Supply Voltage	1.08	1.2	1.32	V
VA12_SYN,					
VA12_RF					.6.
IDD33	3.3V Rating Current (with	-	-	450	mA
	internal regulator and				
	integrated CMOS PA)			. 1	•
IDD_IO	IO Rating Current (including			200	mA
<b>O</b>	VDD_IO)	21			
IDD_IO_33	3.3V IO Rating Current		_	50	mA

# 25.3. Digital IO Pin DC Characteristics

## 25.3.1. Electrical Specifications

Table 25-3 Typical Digital IO DC Parameters (3.3V Case)

Symbol	Parameter	Conditions	Min.	Тур.	Мах.	Units
V <sub>IH</sub>	Input-High Voltage	LVTTL	2.0	-	-	V

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V <sub>IL</sub>	Input-Low Voltage	LVTTL	-	-	0.8	V
V <sub>OH</sub>	Output-High Voltage	LVTTL	2.4	-	-	V
V <sub>OL</sub>	Output-Low Voltage	LVTTL	-	-	0.4	V
I <sub>T+</sub>	Schmitt-trigger High Level		1.78	1.87	1.97	V
I <sub>T</sub> .	Schmitt-trigger Low Level		1.36	1.45	1.56	V
I <sub>IL</sub>	Input-Leakage Current	V <sub>IN</sub> =3.3V or 0	-10	±1	10	μΑ

Table 25-4 Typical Digital IO DC Parameters (1.8V Case)

Symbol	Parameter	Conditions	Min.	Тур.	Мах.	Units
V <sub>IH</sub>	Input-High Voltage	CMOS	0.65x Vcc		-	V
V <sub>IL</sub>	Input-Low Voltage	CMOS		,	0.35x Vcc	V
V <sub>OH</sub>	Output-High Voltage	CMOS	Vcc-0.45	-	-	V
V <sub>OL</sub>	Output-Low Voltage	CMOS		-	0.45	V
I <sub>T+</sub>	Schmitt-trigger High Level		1.02	1.09	1.14	V
I <sub>T</sub> .	Schmitt-trigger Low Level		0.67	0.73	0.87	V
I <sub>IL</sub>	Input-Leakage Current	V <sub>IN</sub> =1.8V or 0	-10	±1	10	μΑ



# 26. Mechanical Dimensions

# 26.1. Package Specification

## 26.1.1. QFN32

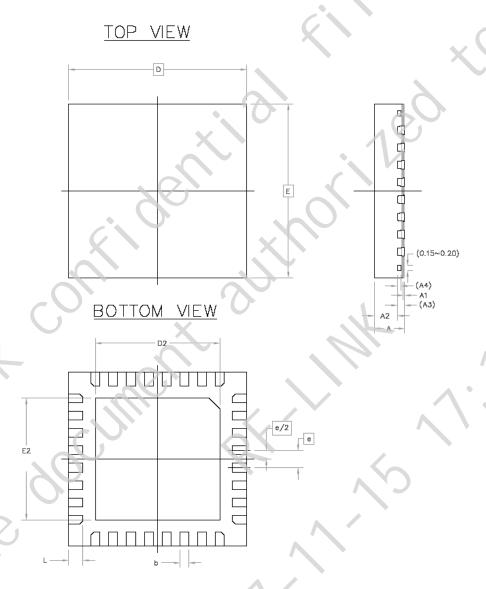


Figure 19 QFN32 Package Specification

Table 26-1 QFN32 Package Specification

Symbol	L	Dimension in mr		D	imension in ind	ch
	Min	Nom	Max	Min	Nom	Max
Α	0.80	0.85	0.90	0.031	0.033	0.035



A1	0.00	0.02	0.05	0.000	0.001	0.002	
A3	0.20 REF			0.008 REF			
A4	0.10 REF			0.004 REF			
b	0.18	0.25	0.30	0.007	0.010	0.012	
D/E	5.00 BSC			0.020 BSC			
D2/E2	3.25	3.50	3.75	0.128	0.138	0.148	
е	0.50 BSC				0.020 BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020	

Notes:

1. CONTROLLING DIMENSION: MILLIMETER(mm).

2. REFERENCE DOCUMENTL: JEDEC MO-220.



## 26.1.2. QFN68

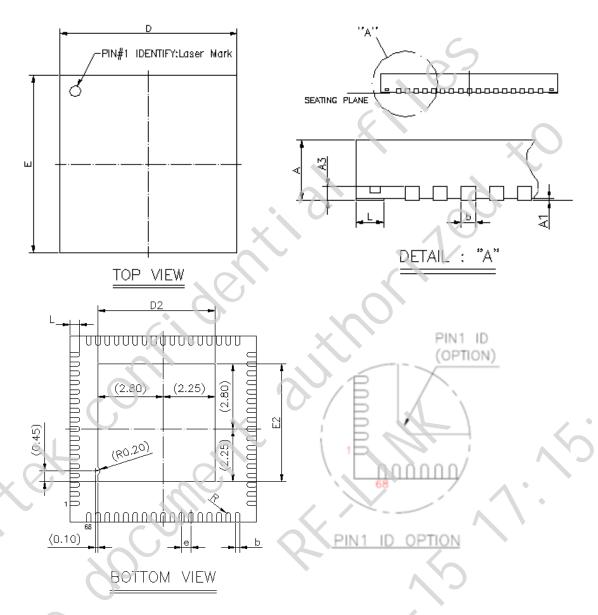


Figure 20 QFN68 Package Specification

Table 26-2 QFN68 Package Specification

Symbol	Dimension in mm				Dimension in inch		
	Min	Nom	Max	Min	Nom	Max	
Α	0.80	0.85	0.90	0.031	0.033	0.035	
<b>A</b> <sub>1</sub>	0.00	0.02	0.05	0.000	0.001	0.002	

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$A_3$	0.2 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D/E	7.90	8.00	8.10	0.311	0.315	0.319
$D_{2}/E_{2}$	4.95	5.05	5.15	0.195	0.199	0.203
е	0.40 BSC			0.016 BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020

### Notes:

1. CONTROLLING DIMENSION: MILLIMETER(mm).

2. REFERENCE DOCUMENTL: JEDEC MO-220.